

### Product Change Notification / NTDO-21XSFE180

# Date:

03-Jan-2023

# **Product Category:**

8-bit Microcontrollers

# PCN Type:

Manufacturing Change

## **Notification Subject:**

CCB 4853 Final Notice: Qualification of MMT as an additional assembly site for selected Atmel ATMEGA324PB device family available in 44L VQFN (7x7x1mm) package using CuPdAu wire.

### Affected CPNs:

NTDO-21XSFE180\_Affected\_CPN\_01032023.pdf NTDO-21XSFE180\_Affected\_CPN\_01032023.csv

# Notification Text:

PCN Status: Final Notification

PCN Type: Manufacturing Change

**Microchip Parts Affected:**Please open one of the files found in the Affected CPNs section. Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:**Qualification of MMT as an additional assembly site for selected Atmel ATMEGA324PB device family available in 44L VQFN (7x7x1mm) package using CuPdAu wire.

#### Pre and Post Change Summary:

Pre Change	Post Change

Assembly Site		ASE Group Chung-Li (ASCL)	ASE Group Chung-Li (ASCL)	Microchip Technology Thailand Branch (MMT)				
MSL Inf	ormation	MSL 3	MSL 3	MSL 1				
Wire n	naterial	CuPdAu/Cu	CuPdAu/Cu	CuPdAu				
Die attac	h material	EN-4900G	EN-4900G	3280				
	compound terial	G700LA	G700LA	G700LTD				
	Material	C194	C194	C194				
Lead	Paddle size	213x213 mils	213x213 mils	213x213 mils				
frame	DAP Surface Prep	Bare Cu	Bare Cu	Bare Cu				
	Design	Please see attached Pre and Post Change comparison						

### Impacts to Data Sheet:None

### Change ImpactNone

**Reason for Change:**To improve on-time delivery performance by qualifying MMT as an additional assembly site using CuPdAu wire.

### Change Implementation Status: In Progress

Estimated First Ship Date: January 30, 2023 (date code: 2305)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

### Time Table Summary:

	September 2021				>	January 2023					
Workweek	3 6	3 7	3 8	3 9	4 0		1	2	3	4	5
Initial PCN Issue Date					х						
Qual Report Availability							х				
Final PCN Issue Date							х				

Estimated Implementation Date										х	
-------------------------------------	--	--	--	--	--	--	--	--	--	---	--

Method to Identify Change: Traceability code

**Qualification Report:**Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report.

**Revision History:**September 26, 2021: Issued initial notification. January 3, 2023: Issued final notification. Attached the Qualification Report. Duplicate CPNs were removed. Revised wire material for ASCL from CuPdAu to CuPdAu/Cu and removed wire material notes. Provided estimated first ship date to be on January 30, 2023.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

## Attachments:

#### PCN\_NTDO-21XSFE180\_Qualification Report.pdf PCN\_NTDO-21XSFE180 Pre and\_Post Change Summary.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

#### **Terms and Conditions:**

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our PCN home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the PCN FAQ section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections. NTDO-21XSFE180 - CCB 4853 Final Notice: Qualification of MMT as an additional assembly site for selected Atmel ATMEGA324PB device family available in 44L VQFN (7x7x1mm) package using CuPdAu wire.

Affected Catalog Part Numbers (CPN)

ATMEGA324PB-MU ATMEGA324PB-MN ATMEGA324PB-MNR ATMEGA324PB-MUR